

MST26P21D

Dual P-Channel 20-V (D-S) MOSFET

Description

The MST26P21D are using trench DMOS technology. This advanced technology has been especially tailored to minimize $R_{DS(ON)}$, provide superior switching performance.

The devices are well suited for high efficiency fast switching applications.

The devices meet the RoHS and Green Product requirement with full function reliability approved.

Features

- Advanced DMOS Trench technology
- Fast Switching
- Suit for 1.8V Gate Drive Applications
- Green Device Available

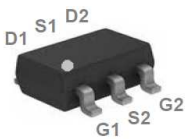
Typical Applications

- Notebook
- Load Switch
- Hand-held Instrument

Package type : SOT-26

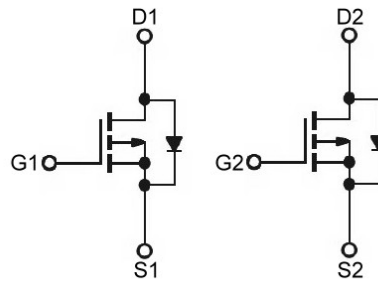
Packing & Order Information

3,000/Reel

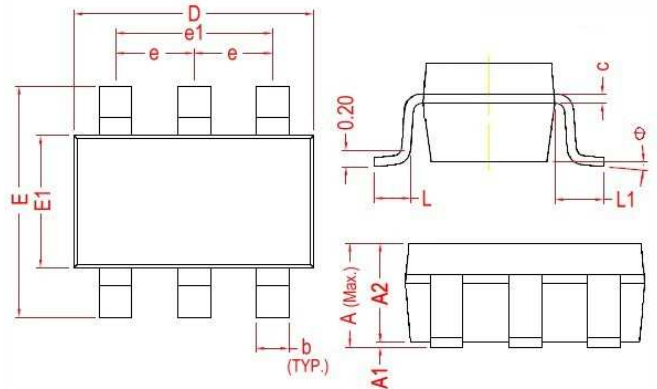


RoHS Compliant

Graphic Symbol

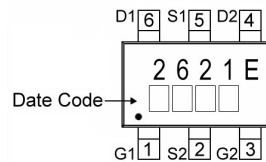


Package Dimension



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	1.45 Max.		L	0.37 Ref.	
A1	0	0.15	L1	0.60 Ref.	
A2	0.90	1.30	θ	0°	10°
c	0.12 Ref.		b	0.30	0.50
D	2.70	3.10	e	0.95 Ref.	
E	2.60	3.00	e1	1.90 Ref.	
E1	1.40	1.80			

Marking



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MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Absolute Maximum Ratings (unless otherwise specified)

Symbol	Parameter	Value	Units
V_{DS}	Drain-Source Voltage	-20	V
V_{GS}	Gate-Source Voltage	± 10	V
I_D	Continuous Drain Current ¹ ($T_A=25^\circ\text{C}$)	-2.5	A
	Continuous Drain Current ¹ ($T_A=70^\circ\text{C}$)	-2.0	A
I_{DM}	Pulsed Drain Current ² ($T_A=25^\circ\text{C}$)	-10	A
P_D	Power Dissipation ³ ($T_A=25^\circ\text{C}$)	1.25	W
T_J/T_{STG}	Operating Junction and Storage Temperature	-55 to +150	$^\circ\text{C}$

Thermal Resistance Ratings

Symbol	Parameter	Maximum	Units
$R_{\theta JA}$	Maximum Junction-to-Ambient ¹	100	$^\circ\text{C/W}$

Electrical Characteristics($T_J=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=-250\mu\text{A}$	-0.3	-0.6	-1.0	V
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0\text{V}$, $I_D=-250\mu\text{A}$	-20	-	-	V
I_{GSS}	Gate-Source Leakage Current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 10\text{V}$	-	-	± 100	nA
I_{DSS}	Drain-Source Leakage Current	$V_{DS}=-20\text{V}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	-	-	-1	μA
		$V_{DS}=-16\text{V}$, $V_{GS}=0\text{V}$, $T_J=125^\circ\text{C}$	-	-	-10	μA
$R_{DS(on)}$	Static Drain-Source On-Resistance ²	$V_{GS}=-4.5\text{V}$, $I_D=-2.5\text{A}$	-	-	90	m Ω
		$V_{GS}=-2.5\text{V}$, $I_D=-2.0\text{A}$	-	-	130	
		$V_{GS}=-1.8\text{V}$, $I_D=-1.0\text{A}$	-	-	180	
V_{SD}	Diode Forward Voltage ²	$I_S=-1\text{A}$, $V_{GS}=0\text{V}$, $T_J=25^\circ\text{C}$	-	-	-1.0	V
I_S	Continuous Source Current ^{1,4} (Diode)	$V_G=V_D=0\text{V}$, Force Current	-	-	-2.5	A
I_{SM}	Pulsed Source Current ^{2,4} (Diode)		-	-	-5.0	

Notes

1. Surface mounted on a 1 inch² FR-4 board with 20Z copper.
2. The data tested by pulsed, pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.
3. The power dissipation is limited by 150 $^\circ\text{C}$ junction temperature.
4. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

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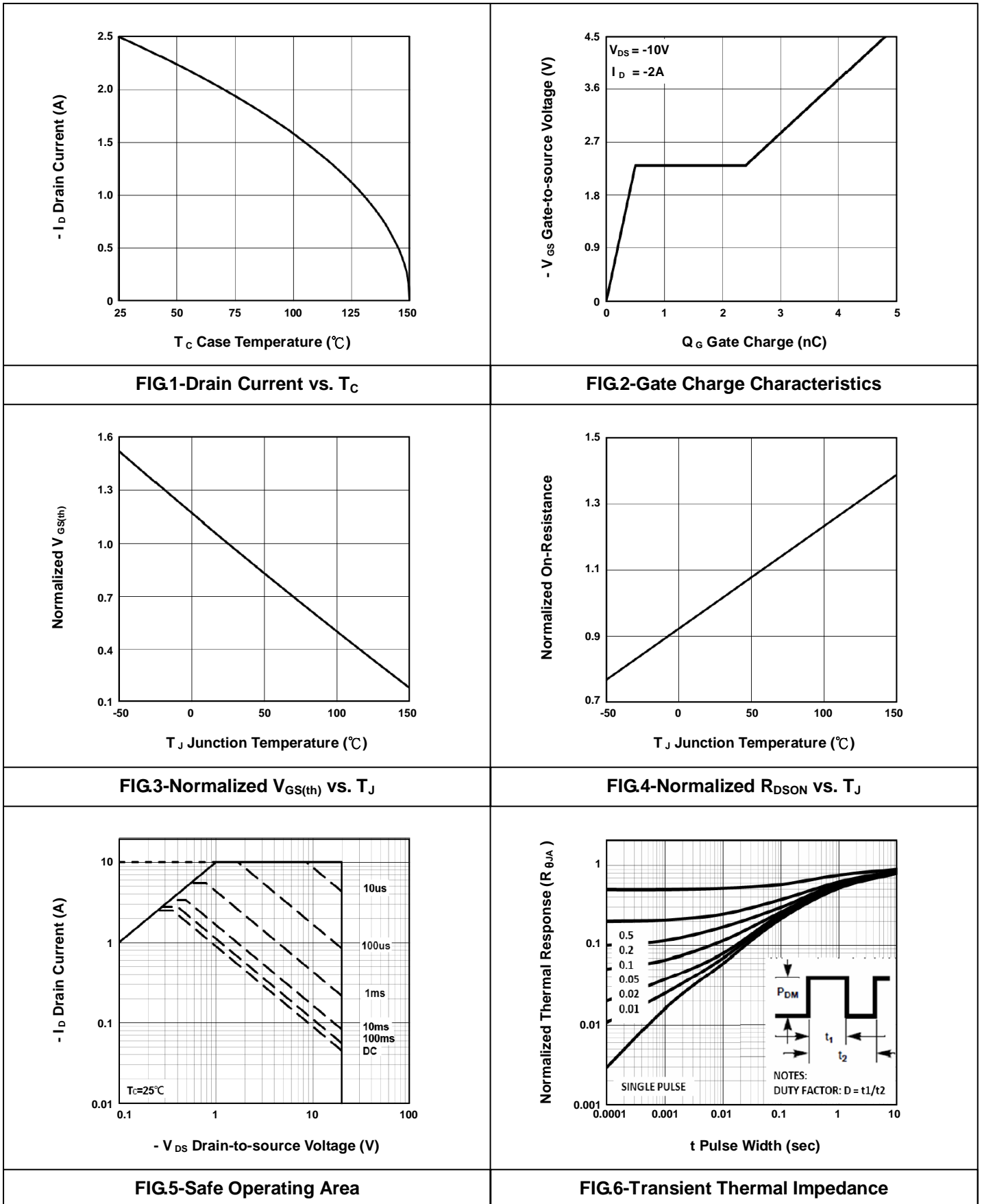
Dynamic and switching Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
Q_g	Total Gate Charge ²	$V_{DS} = -10V$	--	4.8	--	nC
Q_{gs}	Gate-Source Charge	$I_D = -2A$	--	0.5	--	
Q_{gd}	Gate-Drain Charge	$V_{GS} = -4.5V$	--	1.9	--	
$t_{d(on)}$	Turn-On Delay Time ²	$V_{DS} = -10V$	--	3.5	--	ns
t_r	Rise Time	$I_D = -1A$	--	12.6	--	
$t_{d(off)}$	Turn-Off Delay Time	$V_{GS} = -4.5V$	--	32.6	--	
t_f	Fall Time	$R_G = 25\Omega$	--	8.4	--	
C_{ISS}	Input Capacitance	$V_{DS} = -15V$	--	350	--	pF
C_{OSS}	Output Capacitance	$V_{GS} = 0V$	--	66	--	
C_{RSS}	Reverse Transfer Capacitance	$f = 1.0MHz$	--	50	--	

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• Typical Electrical Characteristics



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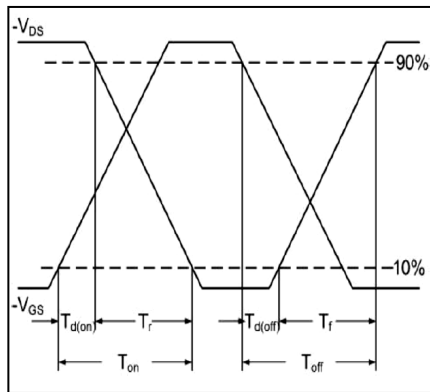


FIG.7-Switching Time Waveform

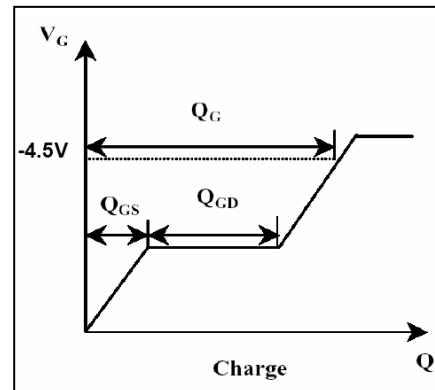


FIG.8-Gate Charge Waveform

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